

STANDARD TRIACS

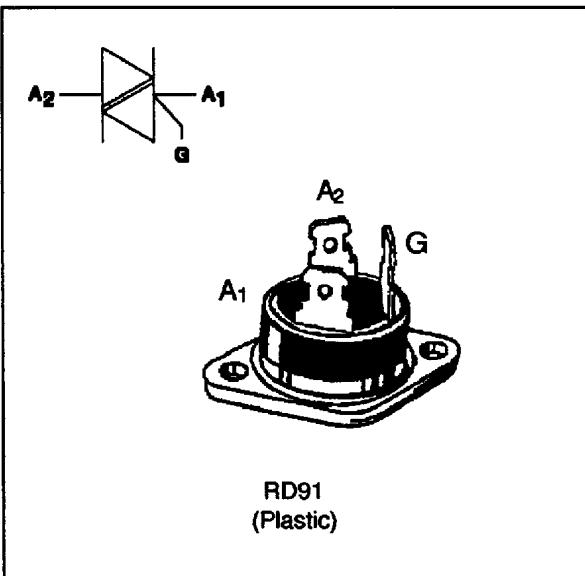
FEATURES

- HIGH SURGE CURRENT CAPABILITY
- COMMUTATION : $(dV/dt)c > 10V/\mu s$
- BTA Family :
- INSULATING VOLTAGE = 2500V_(RMS)
- (UL RECOGNIZED : E81734)

DESCRIPTION

The BTA40 A/B triac family are high performance glass passivated PNPN devices.

These parts are suitable for general purpose applications where high surge current capability is required. Application such as phase control and static switching on inductive or resistive load.



ABSOLUTE RATINGS (limiting values)

Symbol	Parameter	Value	Unit
I _T (RMS)	RMS on-state current (360° conduction angle)	40	A
I _{TSM}	Non repetitive surge peak on-state current (T _j initial = 25°C)	t _p = 8.3 ms	A
		t _p = 10 ms	
I _{2t}	I _{2t} value	t _p = 10 ms	A ² s
dI/dt	Critical rate of rise of on-state current Gate supply : I _G = 500mA diG/dt = 1A/ μ s	Repetitive F = 50 Hz	A/ μ s
		Non Repetitive	
T _{stg} T _j	Storage and operating junction temperature range	- 40 to + 150	°C
		- 40 to + 125	°C
T _I	Maximum lead temperature for soldering during 10 s at 4.5 mm from case	260	°C

Symbol	Parameter	BTA40-... A/B				Unit
		400	600	700	800	
V _{DRM} V _{RRM}	Repetitive peak off-state voltage T _j = 125 °C	400	600	700	800	V

BTA40 A/B

THERMAL RESISTANCES

Symbol	Parameter	Value	Unit
R _{th} (j-c) DC	Junction to case for DC	1.2	°C/W
R _{th} (j-c) AC	Junction to case for 360° conduction angle (F = 50 Hz)	0.9	°C/W

GATE CHARACTERISTICS (maximum values)

P_G (AV) = 1W P_{GM} = 40W (tp = 20 μs) I_{GM} = 8A (tp = 20 μs) V_{GM} = 16V (tp = 20 μs).

ELECTRICAL CHARACTERISTICS

Symbol	Test Conditions	Quadrant		Suffix		Unit
				A	B	
I _{GT}	V _D =12V (DC) R _L =33Ω	T _j =25°C	I-II-III	MAX	100	mA
			IV	MAX	150	
V _{GT}	V _D =12V (DC) R _L =33Ω	T _j =25°C	I-II-III-IV	MAX	1.5	V
V _{GD}	V _D =V _{DRM} R _L =3.3kΩ	T _j =125°C	I-II-III-IV	MIN	0.2	V
t _{gt}	V _D =V _{DRM} I _G = 500mA dI _G /dt = 3A/μs	T _j =25°C	I-II-III-IV	TYP	2.5	μs
I _L	I _G =1.2 I _{GT}	T _j =25°C	I-III-IV	TYP	70	mA
			II		200	
I _H *	I _T = 500mA gate open	T _j =25°C		MAX	100	mA
V _{TM} *	I _{TM} = 60A tp= 380μs	T _j =25°C		MAX	1.8	V
I _{DRM} I _{RRM}	V _{DRM} Rated V _{RRM} Rated	T _j =25°C		MAX	0.01	mA
		T _j =125°C		MAX	6	
dV/dt *	Linear slope up to V _D =67%V _{DRM} gate open	T _j =125°C		MIN	250	V/μs
(dV/dt)c *	(dI/dt)c = 18A/ms	T _j =125°C		MIN	10	V/μs

* For either polarity of electrode A2 voltage with reference to electrode A1.

ORDERING INFORMATION

Package	$I_T(\text{RMS})$	$V_{\text{DRM}} / V_{\text{RRM}}$	Sensitivity Specification	
			A	B
BTA (Insulated)	40	400	X	X
		600	X	X
		700	X	X
		800	X	X

**Fig.1 : Maximum RMS power dissipation versus RMS on-state current ($f=50\text{Hz}$).
(Curves are cut off by $(di/dt)_c$ limitation)**

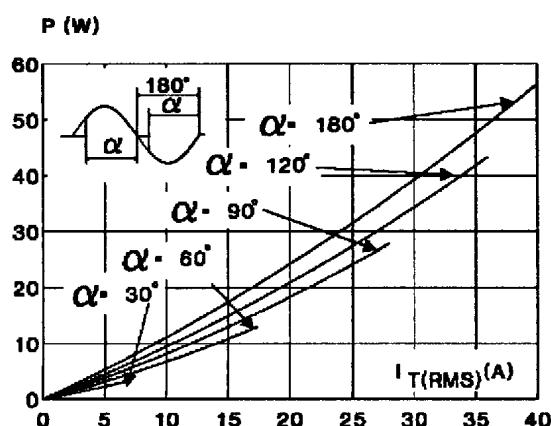


Fig.3 : RMS on-state current versus case temperature.

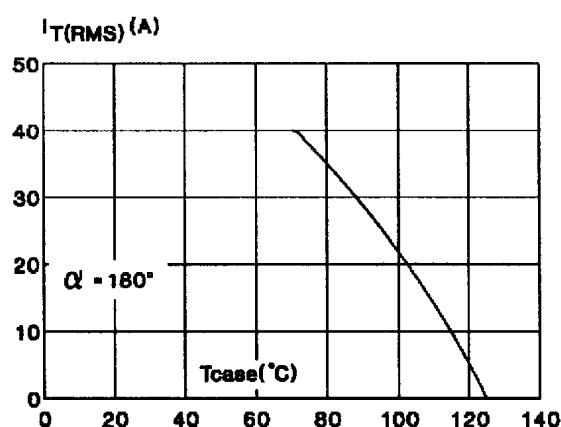


Fig.2 : Correlation between maximum RMS power dissipation and maximum allowable temperatures (T_{amb} and T_{case}) for different thermal resistances heatsink + contact.

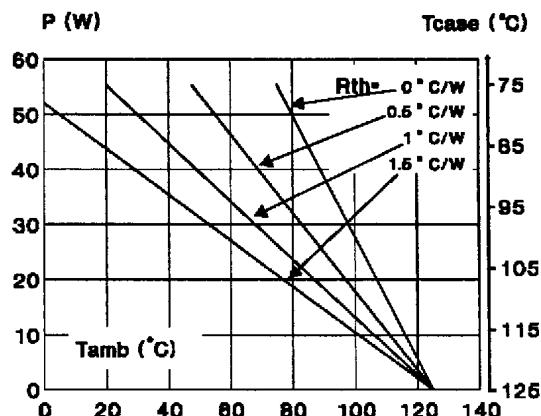
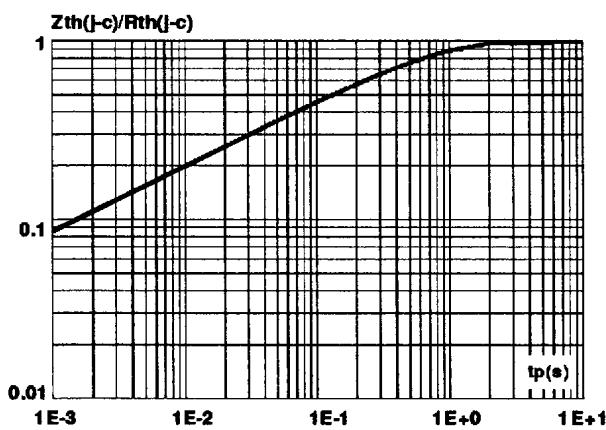


Fig.4 : relative variation of thermal impedance junction to case versus pulse duration.



BTA40 A/B

Fig.5 : Relative variation of gate trigger current and holding current versus junction temperature.

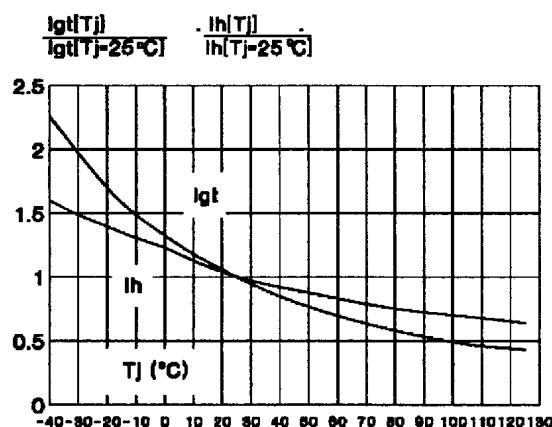


Fig.6 : Non Repetitive surge peak on-state current versus number of cycles.

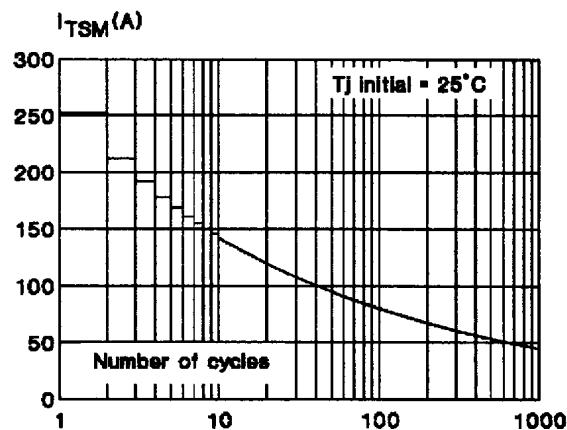


Fig.7 : Non repetitive surge peak on-state current for a sinusoidal pulse with width : $t \leq 10\text{ms}$, and corresponding value of I^2t .

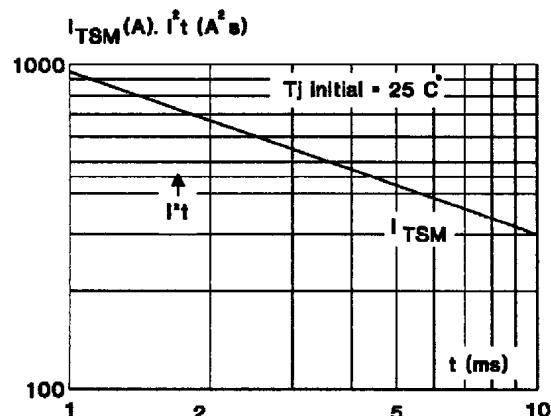
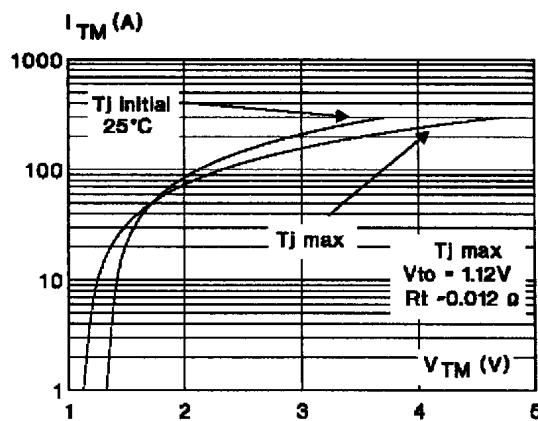
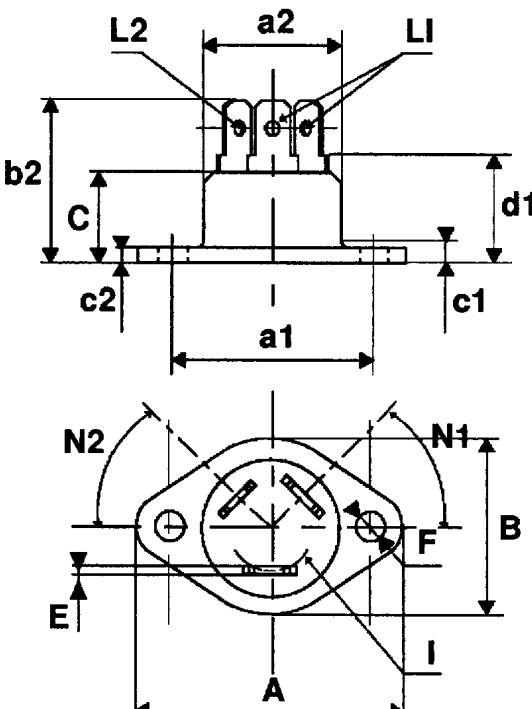


Fig.8 : On-state characteristics (maximum values).



PACKAGE MECHANICAL DATA

RD91 Plastic



REF.	DIMENSIONS			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A		40.00		1.575
a1	29.90	30.30	1.177	1.193
a2		22.00		0.867
B		27.00		1.063
b1	13.50	16.50	0.531	0.650
b2		24.00		0.945
C		14.00		0.551
c1		3.50		0.138
c2	1.95	3.00	0.077	0.118
E	0.70	0.90	0.027	0.035
F	4.00	4.50	0.157	0.177
I	11.20	13.60	0.441	0.535
L1	3.10	3.50	0.122	0.138
L2	1.70	1.90	0.067	0.075
N1	33°	43°	33°	43°
N2	28°	38°	28°	38°

Marking : type number

Weight : 20 g

Information furnished is believed to be accurate and reliable. However, SGS-THOMSON Microelectronics assumes no responsibility for the consequences of use of such information nor for any infringement of patents or other rights of third parties which may result from its use. No license is granted by implication or otherwise under any patent or patent rights of SGS-THOMSON Microelectronics. Specifications mentioned in this publication are subject to change without notice. This publication supersedes and replaces all information previously supplied.

SGS-THOMSON Microelectronics products are not authorized for use as critical components in life support devices or systems without express written approval of SGS-THOMSON Microelectronics.

© 1995 SGS-THOMSON Microelectronics - Printed in Italy - All rights reserved.

SGS-THOMSON Microelectronics GROUP OF COMPANIES

Australia - Brazil - France - Germany - Hong Kong - Italy - Japan - Korea - Malaysia - Malta - Morocco - The Netherlands - Singapore - Spain - Sweden - Switzerland - Taiwan - Thailand - United Kingdom - U.S.A.